Lecture 4 of 4 (13:1)

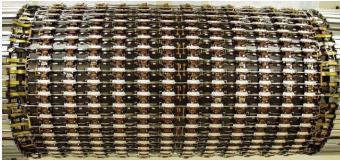
(5.7) Examples from cooling silicon tracking detectors in particle physics (ATLAS, CMS, LHCb)

We've seen some examples from the present running of ATLAS:

- Saturated Fluorocarbons of the form C_nF_(2n+2) like C₃F₈ (current use in most of the ATLAS Silicon tracker) and C₆F₁₄ (current use as liquid coolant in parts of the CMS Silicon tracker) which have respective GWP₂₀ of around 5890 & 6640 x CO₂.
- New upgraded trackers are however being built for the High Luminosity phase of LHC to run from 2029-2041
- A core aim in these detectors is to use low Global Warming Potential coolants
- Any coolant must be non-flammable, non-toxic, non-oxone depleting, (electrically) non-conductive, radiation resistant and have low or zero GWP
- CO₂ cooling is being pushed hard at CERN but has problems of high operating pressure and a limiting evaporating temperature of -56 °C (triple point temperature where 3 phases of CO₂ co-exist (liquid, vapor, solid CO₂ 'snow')

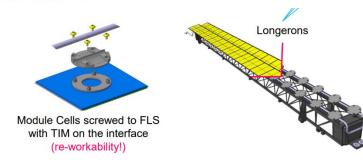
(5.7) Examples from cooling particle physics Si trackers (ATLAS, CMS, LHCb) Two distinct types of detector cooling geometry at HL-LHC:

(1) Tube and block 'DNA'



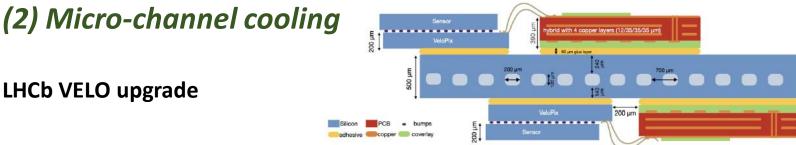
ATLAS barrel SCT (present)

PATHOLIPATIN



ATLAS ITK Barrel longerons and Si module block attachment (future HL-LHC)

Disadvantages: long(er) heat conduction path (more interfaces) Si + cold(er) coolant



Advantages: shortest heat conduction path to coolant: coolant can be warmer: Disadvantages: fraglity issues: channels etched in silicon and cover plate attached

Micro-channel cooling: more on the LHCb VELO upgrade



O.A. de Aguiar Francisco, W. Byczynski, K. Akiba et al.



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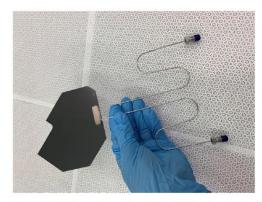
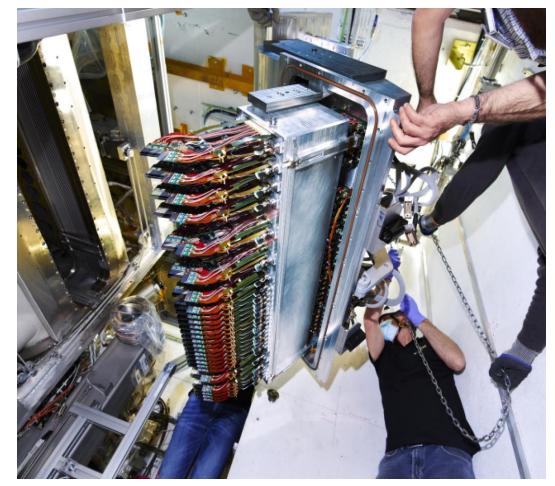


Fig. 20. Microchannel assembly, consisting of a microchannel cooler soldered to a fluidic connector, ready to be equipped with VELO module components.



https://www.youtube.com/watch?v=RmlQwLdfFZg

Micro-channel cooling: more on the LHCb VELO upgrade Recent mastery of evaporative CO₂ cooling in microchannels

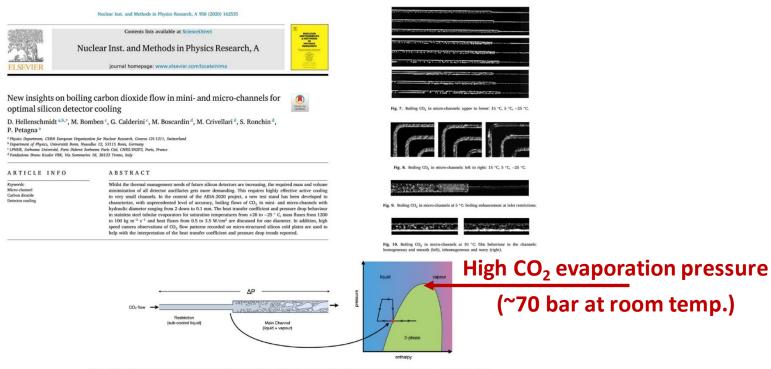
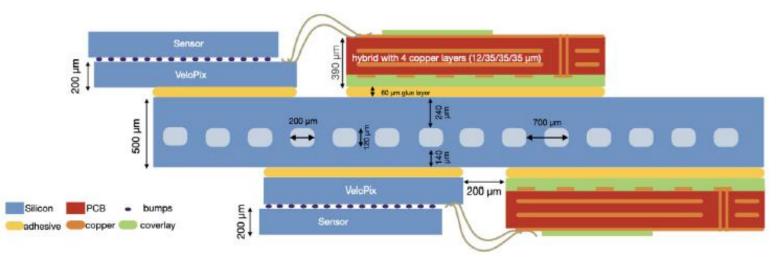


Fig. 2. The left side of the figures shows the typical channel shape for the bi-phase CO₂ microchannel cooling implementation. The pressure drop at the point where the channel expands should bring the coolant to the saturation point as it enters the region of the detector to be cooled. The diagram on the right illustrates the principle of the Two-Phase Accumulator Controlled Loog (2PAC) cooling concepts used in LHOS [6].

https://www.youtube.com/watch?v=hsLXi9QTxUo A film narrated by LHCb physicist Paula Collins

Despite these evident successes, the coolant is not directly passing through the detector chips, just through a heat collector plates onto which they are bonded which contain 200 x 120 micron etched microchannels .



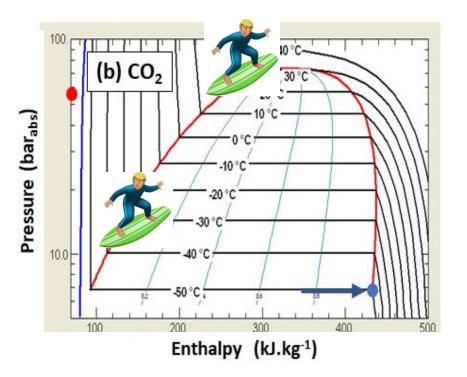
So the silicon pixel detectors and their readout electronics are *almost directly* cooled by fluid evaporating in microchannels.

We can therefore ask:

- will processor chips ever have microchannels etched into them for direct coolant flow?
- will this coolant be liquid, or evaporative for reduced mass flow?
- how would the cooling pipes be connected?
- what would the (necessarily electrically non-conductive) fluid be: a fluorocarbon, CO₂ or a new low GWP fluid, for example from the 3M "NOVEC" range?

The CO₂ problems:

- (1) High evaporation pressure at room temperature (60-70 bar) the detector has to 'surf ' down the saturated liquid line to the operating evaporation temperature of -30 → -40 °C (pressure around 12 18 bars): fatigue cycling an issue in microchannels..?
- (2) The high triple point temperature of -56 °C limits the lowest temperature attainable in the tubes of a tube & block cooling system: may not be cold enough for operation of Si detectors after years of irradiation in the LHC High Luminosity program (2029-41)



Low GWP Alternatives to CO₂:

(1)Noble gases like Xenon and Krypton

- Very expensive and in very short supply, particularly since the war in Ukraine.
- Complex transcritical circulation for Krypton (outside the scope of this unit);
- Xenon probably just squeaks in (~50 bar @ 15 C) but still has relatively high pressure evaporation at room temp, but no triple point problem (-112 °C)

(2) Fluoroketone ($C_n F_{2n} O$) replacements for saturated fluorocarbons ($C_n F_{(2n+2)}$)

• The substitution of two fluorine atoms with an oxygen atom can reduce the GWP to zero: if the oxygen atom is on the end or on a side-arm of the molecule (see next slides);





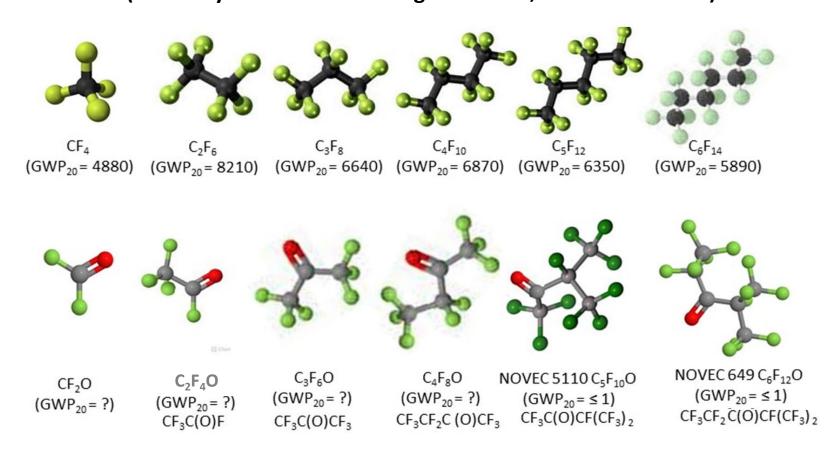
- Ultraviolet scission of the fluoroketone molecules in the upper atmosphere does not create longlived debris molecules (references given in unit support notes);
- $(C_n F_{2n} O)$ molecules with the same number of carbons as their $(C_n F_{(2n+2)})$ partners will have similar thermodynamics (molecular weight difference = 22 units);
- 3M NOVEC 649 (C₆F₁₂O) authorised for use as a C₆F₁₄ replacement at CERN (liquid cooling)

A Fluoroketone ($C_n F_{2n} O$) replacement for a saturated flurorcarbon ($C_n F_{(2n+2)}$)

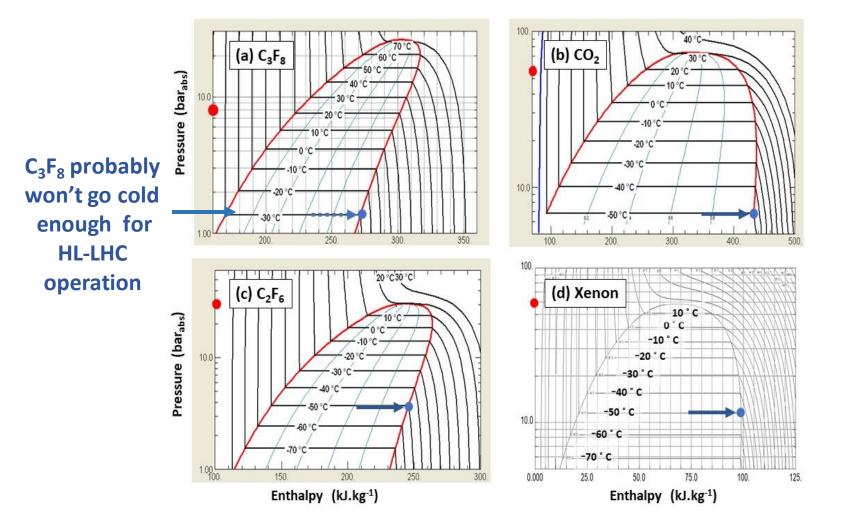
Thermophysical Properties of NOVEC 649 ($C_6F_{12}O$) & C_6F_{14} (at 25°C except where noted: after [7.15])

Fluid thermophysical property	NOVEC 649: $C_2F_5C(O)CF(CF_3)_2$ Perfluoro-2-methyl-3-pentanone ($C_6F_{12}O$ fluoro-ketone)	C ₆ F ₁₄ (Perfluorohexane, Saturated fluorocarbon)
Boiling temp @ 1 atm (°C)	49	56
Critical Temp (°C)	169	178
Critical Pressure (MPa)	1.87	1.89
Freezing temperatre (°C)	<-100	< -100
Specific heat (J.kg ⁻¹ K ⁻¹)	1103	1050
Density (kg.m ⁻³)	1610	1680
Kinematic viscosity (cSt)	0.42 NOVEC 649 C6F120	0.4
Latent Heat (J.kg ⁻¹)	(GWP ₂₀ = ≤ 1) CF ₃ CF ₂ C(0)CF(CF ₃)	00 (CMD 5000)
Vapour Pressure @ 25 °C (kPa)	40.4	30.9
Vapour Pressure @ 100 °C (kPa)	441	350
Water solubility (ppm _w)	21	10

Saturated fluorocarbons (C_nF_(2n+2)) and their Spurred fluoroketone (C_nF_{2n}O) analogs (with 20 year Global Warming Potentials, where measured)



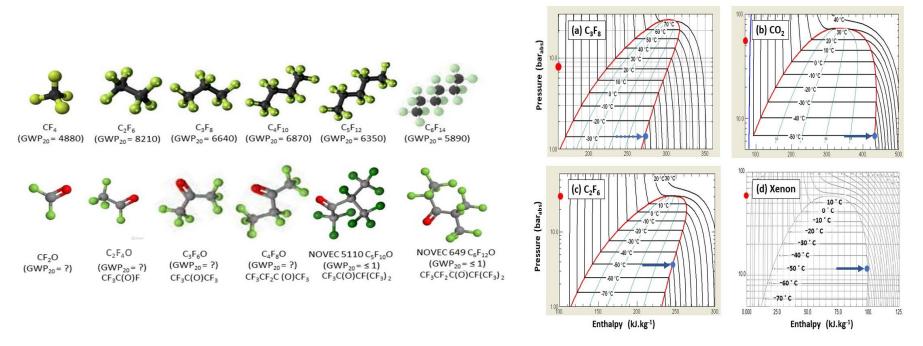
Some Thermodynamic comparisons two convenient SFCs, CO₂, Xe (F-K thermodynamics should be similar to same carbon order SFCs)



(5.7) SWOT analysis of cooling fluids HL-LHC

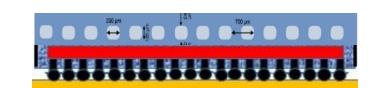
Strengths CO ₂ Non-flammable, non-toxic, electrical insulator, non- ozone-depleting, radiation resistant, GWP=1	Weaknesses CO ₂ High pressure circulation (60 bar) at ambient temp before cooldown to operating temp High triple point (-56°C)	Strengths C ₂ F ₆ Non-flammable, non-toxic, electrical insulator, non- ozone-depleting, radiation resistant	Weaknesses C ₂ F ₆ Very high GWP (around 6000 x CO ₂)
Threats CO ₂ High triple point may make Si tracker operation problematic: less thermal 'headroom' after heavy irradiaton ('thermal runaway' phenomenon)	Opportunities CO ₂ Extensive R&D program at CERN Evaporative coolant of choice for ATLAS, CMS for start of HL- LHC program	Threats C ₂ F ₆ Production will be phased out unless a strong motivation from semiconductor manufacture industry	Opportunities C_2F_6 Proved to decrease the operating temp of an ATLAS SCT thermal model in blend with 75% C_3F_8
Strengths xenon Non-flammable, non-toxic, electrical insulator, non- ozone-depleting, radiation resistant, GWP=0	Weaknesses xenon High pressure circulation (50 bar) at ambient temp before cooldown to operating temp (amost transcritical)	Strengths C _n F _{2n} O Non-flammable, non-toxic, electrical insulator, non-ozone- depleting, radiation resistant, GWP=0	Weaknesses C _n F _{2n} O
Threats xenon	Extremely expensive Opportunities xenon	Threats C _n F _{2n} O Large scale industrial	Opportunities C _n F _{2n} O Expertise in particle physics
Very difficult future procurement (war in Ukraine) (10 ⁻⁸ atmospheric content.)	Could find expertise In particle physics community for fabrication of circulators: already used in dark matter experiments	production may depend on the phasing-out of SFCs, needs of semiconductor manufacture industry: Material compatibility needs further study.	community for 3M NOVEC 649 (C ₆ F ₁₂ O)

- Last problem (6): See separate sheet one for the sleuth:
- while a new fluid C_3F_6O would have all the advantages of C_3F_8 , but with zero GWP, the thermodynamics of C_3F_8 and presumably of C_3F_6O (which differs in molecular weight by 22 units) is not perfect for cooling a processor chip at room temperature. What fluid in the $C_nF_{2n}O$ spectrum might be better, and why?
- Hint: the figures below may help in this.

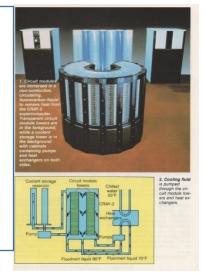


So where does this leave the option of immersion cooling of processors, or the cooling of processor chips themselves thru microchannels?

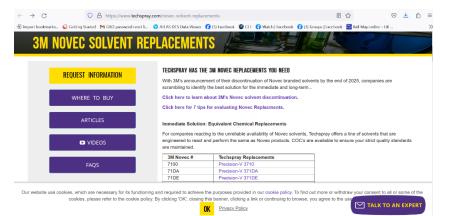




Electrical connections to computer mother board Will processor chips ever look like this? Can semiconductor lithography, implantation, microchannel etch, sealing and connectivity be achievable in one final device?



3M seem to have lost enthusiasm to produce any more fluorinated fluids after 2025, but companies like F2 Chemicals (Preston, UK), Astor (Ru), Synquest (FL), Techspray (GA) continue (probably many others: e.g.China)



Note *Some 3M `NOVEC' fluids are HFCs with GWPs in the ranges of hundreds: **Better to concentrate on $C_n F_{2n}O$ molecules over the full carbon spectrum with GWP = 0. But the needs of the semiconductor & electronics industries will be determinant...